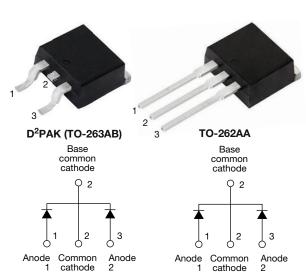
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COMPLIANT HALOGEN

FREE

Ultrafast Rectifier, 2 x 8 A FRED Pt®



VS-MURB1620CTHM3

VS-MURB1620CT-1HM3

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 8 A					
V_{R}	200 V					
V _F at I _F	0.895 V					
t _{rr} (typ)	19 ns					
T _J max.	175 °C					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Common cathode					

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Meets JESD 201 class 1 whisker test
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

MUR.. series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

MECHANICAL DATA

Case: D²PAK (TO-263AB), TO-262AA

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS								
PARAMETER		SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Peak repetitive reverse voltage		V_{RRM}		200	V			
Average restified forward average		1		8.0				
Average rectified forward current	total device	I _{F(AV)}	Rated V _R , T _C = 150 °C	16	۸			
Non-repetitive peak surge current per leg		I _{FSM}		100	А			
Peak repetitive forward current per leg		I _{FM}	Rated V _R , square wave, 20 kHz, T _C = 150 °C	16				
Operating junction and storage terr	nperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	PARAMETER SYMBOL TEST CONDITIONS				MAX.	UNITS		
Breakdown voltage, blocking voltage	V_{BR}, V_{R}	$I_R = 100 \mu A$	200	-	-			
Forward voltage	V	I _F = 8 A	-	-	0.975	V		
	V _F	I _F = 8 A, T _J = 150 °C	-	-	0.895			
Reverse leakage current	I _R	$V_R = V_R$ rated	-	-	5	μA		
neverse leakage current		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	250	μΑ		
Junction capacitance	C _T	$V_{R} = 200 \text{ V}$	-	25	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ		

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1.0 \text{ A}, dI_F/dt = 10$	0 A/μs, V _R = 30 V	-	19	-		
Reverse recovery time	t _{rr}	T _J = 25 °C	$I_F = 8 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_B = 160 \text{ V}$	-	20	-	ns A	
		T _J = 125 °C		-	34	-		
Dook rooman current		T _J = 25 °C		-	1.7	-		
Peak recovery current	I _{RRM}	T _J = 125 °C		-	4.2	-		
Reverse recovery charge	0	T _J = 25 °C	- VR - 100 V	-	23	-	nC	
	Q_{rr}	T _J = 125 °C		-	75	-	110	

THERMAL - MECHANIC	THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Maximum junction and storage temperature range	T_J , T_{Stg}		-65	-	175	°C			
Thermal resistance, junction to case per leg	R _{thJC}		-	-	3.0				
Thermal resistance, junction to ambient per leg	R _{thJA}		-	-	50	°C/W			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-				
Weight			-	2.0	-	g			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Madia da la		Case style D ² PAK (TO-263AB)	MURB1620CTH						
Marking device		Case style TO-262AA		MURB16	20CT-1H				

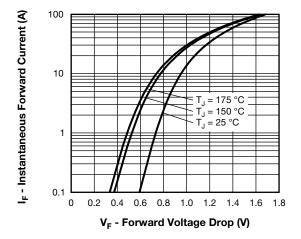


Fig. 1 - Typical Forward Voltage Drop Characteristics

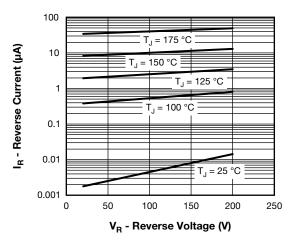


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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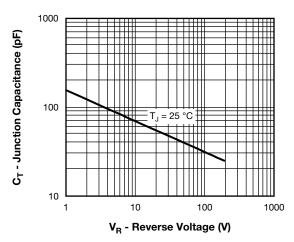


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

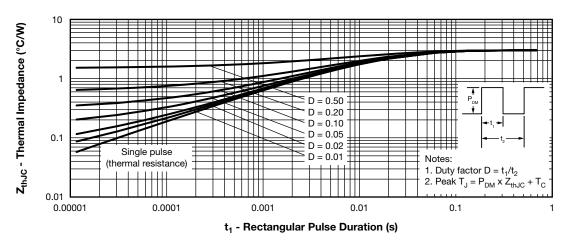


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

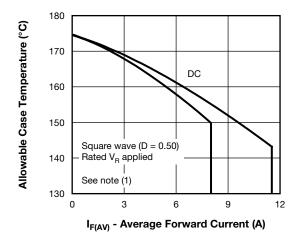


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

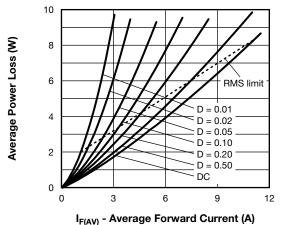


Fig. 6 - Forward Power Loss Characteristics

Note

⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; $Pd = forward power loss = I_{F(AV)} \times V_{FM} at (I_{F(AV)}/D)$ (see fig. 6); $Pd_{REV} = inverse power loss = V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = rated V_R$

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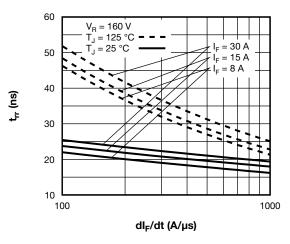


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

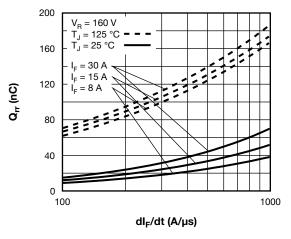
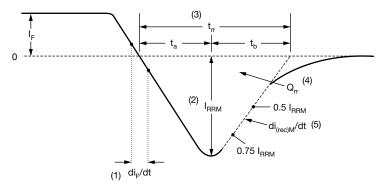


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_{r}$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

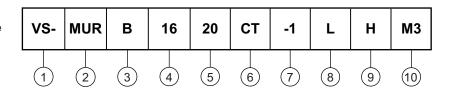
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Ultrafast MUR series

4 - Current rating (16 = 16 A)

5 - Voltage rating (20 = 200 V)

6 - CT = center tap (dual)

7 - • None = D²PAK

• -1 = TO-262

8 - • None = tube (50 pieces)

• L = tape and reel (left oriented, for D²PAK package)

• R = tape and reel (right oriented, for D²PAK package)

9 - H = AEC-Q101 qualified

10 - Environmental digit:

• M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-MURB1620CTHM3	50	Antistatic plastic tube					
VS-MURB1620CT-1HM3	50	Antistatic plastic tube					
VS-MURB1620CTLHM3	800	13" diameter reel					
VS-MURB1620CTRHM3	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS						
Dimensions	TO-263AB (D ² PAK)	www.vishay.com/doc?95046				
Differsions	TO-262AA	www.vishay.com/doc?95419				
Part marking information	TO-263AB (D ² PAK)	www.vishay.com/doc?95444				
	TO-262AA	www.vishay.com/doc?95443				
Packaging information	TO-263AB (D ² PAK)	www.vishay.com/doc?95032				
SPICE model		www.vishay.com/doc?96995				



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES		SYMBOL	MILLIMETERS		INC	INCHES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

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TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	METERS	INC	INCHES		
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.100	BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.36	3.71	0.132	0.146		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- 5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

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